

Roadmap to 50uM Probe Pitch

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Scott Carlin June 4, 1997



Probe Pitch Definition

The bonding pad center to center line dimension.





Why 50uM pitch?

Die are still shrinking and probe has to keep pace.

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Probe Card Supplier Excellence

Consistently deliver cards that allow probe areas to:

Ship ALL the good die and ONLY the good die.

On time at a reasonable cost

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Critical Process Path

- Gather customer information
- Develop design specifications
- Generate "Build Solution"
- Execute manufacturing processes
- Implement performance testing
- Perform data analysis
- Make necessary adjustments





Objective

Design, manufacture, and test 200 point 50uM stagger and straight probe cards using proven fine pitch design rules.

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Design Specifications

- Straight build
- .8 mil tip diameter
- 4 grams per mil force (10%BCF)
- 1.5 mils overdrive
- +/- .25 mil alignment
- +/- .25 mil planarity
- < 20nA leakage @ 10v



Limitations of manufacture

Stagger layout

Straight layout

- Materials (none)
- Methods (alignment)
- Machines (none)

- Materials (mylar)
- Methods (alignment)
- Machines (analyzer)



Remedies

- Custom fixture
- Custom ring
- CAD modeled "Build Solution"
- "Special" 50uM straight mylar
- ITC 1 mil post



Results

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A 50uM stagger probe card exists and has been tested!

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What's Next?

More testing!!!

Gram force

Electrical

Life

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50uM Conclusion

	Stagger	Straight
Can it be built?	Yes	Not yet
Can it be tested?	Yes	Maybe
Is it serviceable?	It depends	Don't know
Can it be used on a probe floor?	Needs testing	Not now
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